

Appl. No. 10/807,210  
Amtd. Dated Feb. 28, 2006  
Reply to Office Action of Nov. 29, 2005

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (previously presented): A method for manufacturing an EMI-shielding (electromagnetic interference-shielding) assembly having a substrate, comprising the steps of:

- (a) providing oxygen plasma to clean the substrate;
- (b) ion plating the cleaned substrate with a layer of nickel or phosphorus nickel to form an adhesion layer;
- (c) ion plating the plated substrate with a metal shielding layer; and
- (d) ion plating the plated substrate with a corrosion-resistant layer.

Claim 2 (previously presented): The method of claim 1, wherein the temperature of the substrate is maintained below 80 °C during any one or more of steps (b), (c), and (d).

Claim 3 (previously presented): The method of claim 1, wherein any one or more of steps (b), (c), and (d) is performed using a vacuum chamber, and a vacuum pressure of the vacuum chamber is maintained between  $1 \times 10^{-6}$  and  $1 \times 10^{-8}$  Torr.

Claim 4 (previously presented): The method of claim 1, wherein step (a) is performed using a vacuum chamber, and oxygen gas is introduced into the vacuum chamber at a volumetric flow rate of between

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200 and 2000 standard cubic centimeters per minute (SCCM).

**Claim 5 (canceled)**

**Claim 6 (currently amended):** The method of claim [5] 1, wherein in step (c) the metal shielding layer is made of copper.

**Claim 7 (original):** The method of claim 6, wherein in step (d) the corrosion-resistant layer is made of stainless steel.

**Claims 8-9 (canceled)**

**Claim 10 (currently amended):** A method for manufacturing an EMI-shielding (electromagnetic interference-shielding) assembly having a substrate, comprising the steps of:

(a) cleaning the substrate;

(b) ion plating the cleaned substrate with an adhesion layer made of nickel or phosphorus nickel; and

(c) ion plating the plated substrate with a shielding layer made of a second metal material.

**Claim 11 (previously presented):** The method of claim 10, wherein after step (c), the substrate is ion plated with a corrosion-resistant layer comprising stainless steel.

**Claim 12 (original):** The method of claim 10, wherein in step (a), the substrate is cleaned using oxygen plasma.

**Claim 13 (previously presented):** The method of claim 10, wherein the second metal material is copper.

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**Claim 14 (withdrawn):** An EMI-shielding assembly, comprising:  
a substrate made of plastic material;  
an adhesion layer applied to the substrate;  
a metal shielding layer adhered to the adhesion layer of the substrate;  
and  
a corrosion-resistant layer adhered to the metal shielding layer.

**Claim 15 (withdrawn):** The EMI-shielding assembly of claim 14,  
wherein the adhesion layer is made of nickel.

**Claim 16 (withdrawn):** The EMI-shielding assembly of claim 14,  
wherein the adhesion layer is made of phosphorus nickel.

**Claim 17 (withdrawn):** The EMI-shielding assembly of claim 15,  
wherein the adhesion has a thickness of  $5 \times 10^{-9}$  to  $10 \times 10^{-9}$  meters.

**Claim 18 (withdrawn):** The EMI-shielding assembly of claim 14,  
wherein the metal shielding layer is made of copper.

**Claim 19 (withdrawn):** The EMI-shielding assembly of claim 18,  
wherein the metal shielding layer has a thickness of  $3 \times 10^{-7}$  to  $6 \times 10^{-7}$   
meters.

**Claim 20 (withdrawn):** The EMI-shielding assembly of claim 14,  
wherein the corrosion-resistant layer is made of stainless steel and has a  
thickness in the range of  $2 \times 10^{-8}$  and  $20 \times 10^{-8}$  meters.

**Claim 21 (withdrawn):** The EMI-shielding assembly of claim 14,  
wherein said adhesion layer is made of metal.

**Claim 22 (previously presented):** The method of claim 1, wherein

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the adhesion layer has a thickness of  $5 \times 10^{-9}$  to  $10 \times 10^{-9}$  meters.

Claim 23 (previously presented): The method of claim 6, wherein the metal shielding layer has a thickness in the range from  $3 \times 10^{-7}$  to  $6 \times 10^{-7}$  meters.

Claim 24 (previously presented): The method of claim 7, wherein the corrosion-resistant layer has a thickness in the range from  $2 \times 10^{-8}$  and  $20 \times 10^{-8}$  meters.